MGV2520124R7M-10

PHYSICAL DIMENSIONS:

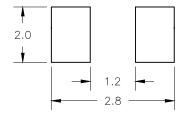
A 2.50 ± 0.20

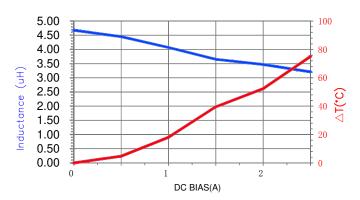
B 2.00 ± 0.20

C 1.20 Max.

 $D = 0.60 \pm 0.30$

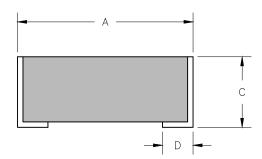
LAND PATTERNS FOR REFLOW SOLDERING



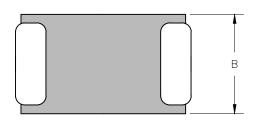


ELECTRICAL SPECIFICATION @ 25°C

	Min	Norm	Max
INDUCTANCE (uH) L @ 1MHz/1mA ±20%	3.76	4.70	5.64
DCR (Ω)		0.196	0.235
Saturation Current Isat (A)		1.90	1.58
Heating Current Irms (A)		1.55	1.40







NOTES:

- 1. COMPONENTS SHOULD BE ADEQUATELY PREHEATED BEFORE SOLDERING.
- 2. TERMINATION FINISH IS 100% TIN.
- 3. OPERATING TEMPERATURE RANGE: $-40^{\circ}\text{C} \sim +125^{\circ}\text{C}$.
- 4. STORAGE TEMPERATURE RANGE: -50° C $\sim +125^{\circ}$ C.
- 5. ISat MEANS THAT MAX DC CURRENT WILL CAUSE A PROXIMATELY 30% INDUCTANCE REDUCTION FROM INITIAL VALUE.
- 6. Irms MEANS THAT MAX DC CURRENT WILL CAUSE PROXIMATELY 40°C TEMPERATURE RISE FROM 25±5°C AMBIENT.

	DIMENSIONS ARE IN mm.			This print is the property of Laird				
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